Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP ProBook 5310m Notebook PC

Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries CCFL</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screw driver</td>
<td>philip #1</td>
</tr>
<tr>
<td>Description #2 screw driver</td>
<td>T8</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove battery module
2. Remove bottom door
3. Remove HDD module.
4. Remove RAM module.
5. Remove Mini-Card.
6. Remove BT module.
7. Remove Keyboard.
8. Remove Log-Up-assy (with T/P & T/P FFC & T/P button assy & APP pcb & ESD pcb)
9. Remove USB pcb (with USB cable).
10. Remove DC-IN pcb & M/B (with thermal module & Fan module).
11. Remove Display-assy (with LVDS, antenna, webcam, microphone, hinge, panel).
12. Remove speaker.
14. Divide RTC battery.
15. Divide Log-Up-assy - Log-Up, APP pcb, T/P button assy, Touch Pad, T/P FFC, ESD pcb)
17. Divide Display-assy - display-bezel, hinge, panel, LVDS, antenna, microphone, webcam.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Push `battery_latch_knob` to remove battery.

2. Remove battery module
2. Divide the screws to remove the bottom door.
3. Divide the screws to remove HDD module.

4. Remove DDR module.
5. Divide the screws and remove the Mini card (WLAN & WWAN).

6. Remove BT module
7. Divide the screws and push K/B bottom side to remove K/B.
8. Divide the screws to remove Log UP assy.
1. Divide screws

2. Divide screws

3. Remove Log UP assy
9. Divide the screws to remove M/B & DC-IN pcb.

10. Divide the screws to remove USB pcb and divide cable.
11. Divide the screws to remove Display assy.

12. Divide the screws to remove speaker.
13. Divide the screws and pull out Fan wire, then remove the thermal module. Pull out DC-IN cable to remove DC-IN pcb.
14. Divide RTC battery.

15. Divide the screw to remove APP pcb.
Divide the screw to remove T/P Btn assy and T/P module.

1. Divide screws
2. Remove T/P Btn assy
3. Remove T/P module
16. Divide HDD brk, HDD module

Remove ESD pcb.
17. Divide the screw bumper and screws to remove Display Bezel assy.
Divide the screws to remove Display hinge L & R assy.

Remove the Panel and LVDS cable.
Remove Webcam.
Remove Antenna cable, then remove Microphone.
1. Remove Panel

2. Remove LVDS cable

3. Remove Webcam

4. Remove Antenna cable and microphone